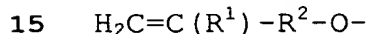


CLAIMS

1. A curable resin composition comprising:

- (I) a reactive silicon group-containing polyoxyalkylene
 5 polymer wherein a introduction rate of a reactive silicon group
 into a molecular terminus is not less than 85% as determined
 by $^1\text{H-NMR}$ analysis, and
 (II) an epoxy resin.

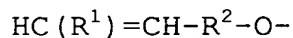
10 2. The curable resin composition according to Claim 1
 wherein the reactive silicon group-containing
 polyoxyalkylene polymer (I) is obtainable by reacting (a) a
 polyoxyalkylene polymer terminating in an unsaturated group of
 either the general formula (1):



(1)

in the formula R^1 represents a hydrocarbon group containing not
 more than 10 carbon atoms; R^2 represents a bivalent organic group
 containing 1 to 20 carbon atoms which contains one or more members
 selected from the group consisting of hydrogen, oxygen and
 20 nitrogen as the constituent atom,

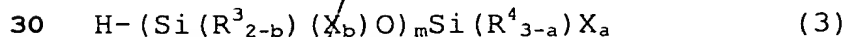
or the general formula (2):



(2)

in the formula R^1 represents a hydrocarbon group containing not
 more than 10 carbon atoms; R^2 represents a bivalent organic group
 25 containing 1 to 20 carbon atoms which contains one or more members
 selected from the group consisting of hydrogen, oxygen and
 nitrogen as the constituent atom,

with (b) a reactive silicon group-containing compound
 of the general formula (3):



in the formula R^3 and R^4 each represents an alkyl group containing
 1 to 20 carbon atoms, an aryl group containing 6 to 20 carbon
 atoms, an aralkyl group containing 7 to 20 carbon atoms, or a
 triorganosiloxy group of the formula $(\text{R}')_3\text{SiO}-$; when two or more
 35 R^3 or R^4 groups are present, they may be the same or different;

R' represents a univalent hydrocarbon group of 1 to 20 carbon atoms; the three of R' groups may be the same or different; X represents a hydroxyl group or a hydrolyzable group; when two or more X groups are present, they may be the same or different;
 5 a represents 0, 1, 2 or 3; b represents 0, 1 or 2; b may be the same or different over m repeats of $-Si(R^{3-b})(X_b)-O-$; m represents an integer of 0 through 19; provided, however, that the condition of $a + \sum b \geq 1$ is satisfied,

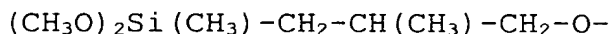
(c) in the presence of a Group VIII transition metal catalyst.

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3. The curable resin composition according to Claim 1 or

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wherein a reactive silicon group-containing molecular chain terminus of the reactive silicon group-containing
 15 polyoxyalkylene polymer (I) is represented by the following formula:



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4. The curable resin composition according to Claim 1 to 3

comprising a compound having both a functional group capable of reacting with an epoxy group and a reactive silicon group

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or a compound having both an epoxy group and a reactive silicon group.

SUB
A2